

SYSTEM FOR ASSEMBLING COMPONENTS OF SUBSTRATE PROCESSING
APPARATUS AND METHOD FOR ASSEMBLING COMPONENTS OF SUBSTRATE
PROCESSING APPARATUS

ABSTRACT

In a system for mounting a component of a substrate processing apparatus on the substrate processing apparatus, a robot transfers the component to a specified position in the substrate processing apparatus. An image sensor obtains an image of the component and an upper
5 surface of a substrate support in the semiconductor manufacturing apparatus. A measurer calculates, based on the image, at least four distances each between one of at least two measurement points on the component and one of at least two reference points on the upper surface of the substrate support. A controller controls the robot and causes the robot to transfer the component to the specified position based on a result of comparison of each of the at least
10 four distances with the corresponding one of at least four predetermined reference distances. Each reference distance is a predetermined distance between one of the at least two measurement points on the component at the specified position and one of the at least two reference points on the upper surface of the substrate support.

Fig. 1